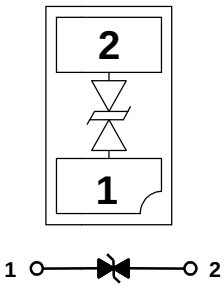
Features

- 140 Watts Peak Pulse Power per Line (tp = 8/20μs)
- Working voltages:12V
- Low Leakage Current
- Low operating and clamping voltages
- Lead Free/RoHS compliant
- Solid-state silicon avalanche technology
- Provides ESD protection to IEC61000-4-2(ESD): ±25kV (air discharge), ±25kV (contact discharge)

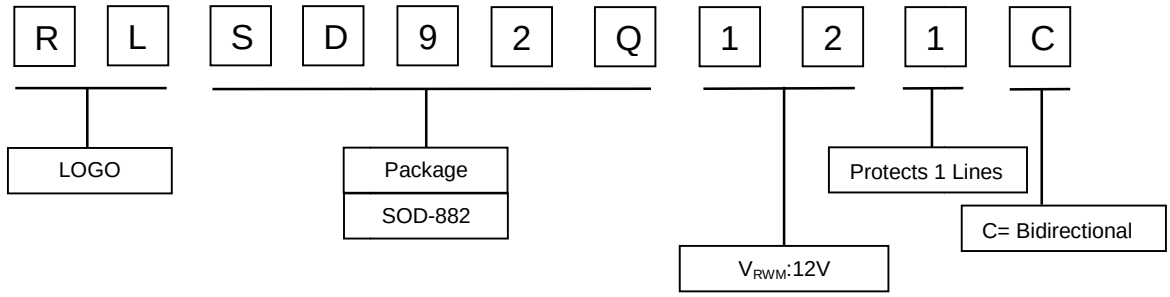
Applications

- Video I/O ports protection
- Set Top Boxes
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Pagers Peripherals

Electrical symbol



Part Number Code



Absolute Maximum Rating

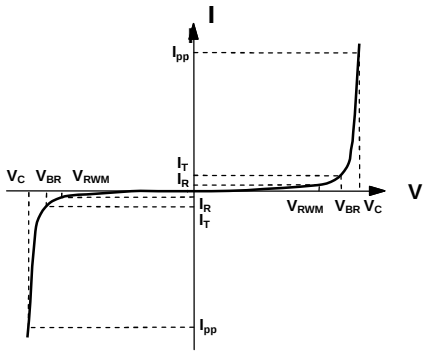
Rating	Symbol	Value	Units
Max. Peak Pulse Power (tp =8/20μs)	P_{PK}	140	Watts
ESD Voltage (Contact)	V_{ESD}	±25	Kv
ESD Voltage (Air)	V_{ESD}	±25	Kv
Lead Solder Temperature - Max . (10 Second Duration)	T_L	260	°C
Operating Temperature	T_J	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Electrical Characteristics (@ 25°C Unless Otherwise Specified)

Type Number	Reverse Stand-Off Voltage	Minimum Breakdown Voltage	Max. Peak Pulse Voltage @8/20μS	Max. Peak Pulse Current @8/20μS	Max. Reverse Leakage @V_{RWM}	Typical Capacitance
	V_{RWM}	V_{BR} @1mA	V_C@ Max. I_{PP}	I_{PP}	I_R@V_{RWM}	DC=0V C_J@ 1 MHz
	V	V	V	A	μA	pF
RLSD92Q121C	12	13.3	23.6	6.3	1.0	10

Electrical Parameters (T=25°C)

Symbol	Parameter
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Characteristic Curves

Fig 1. 8/20μs Pulse Waveform

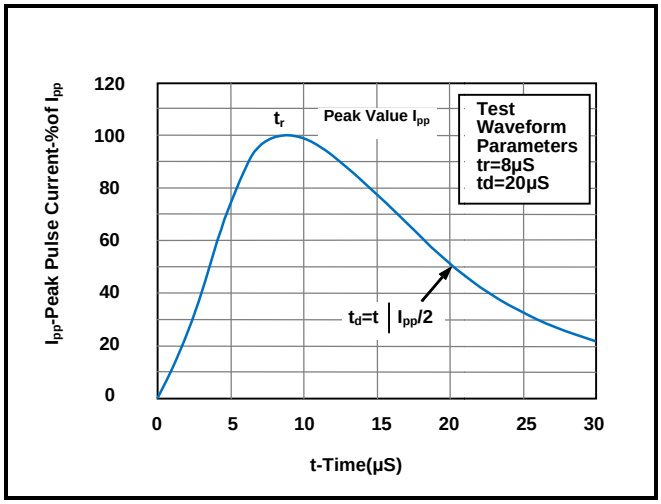


Fig2.ESD Pulse Waveform (according to IEC61000-4-2)

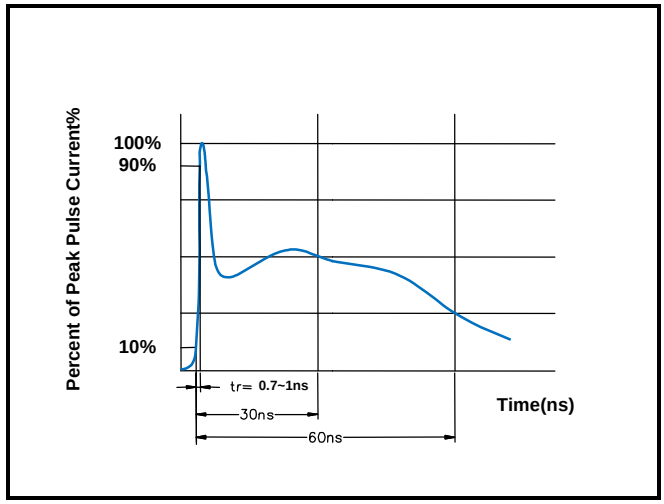


Fig 3. Power Derating Curve

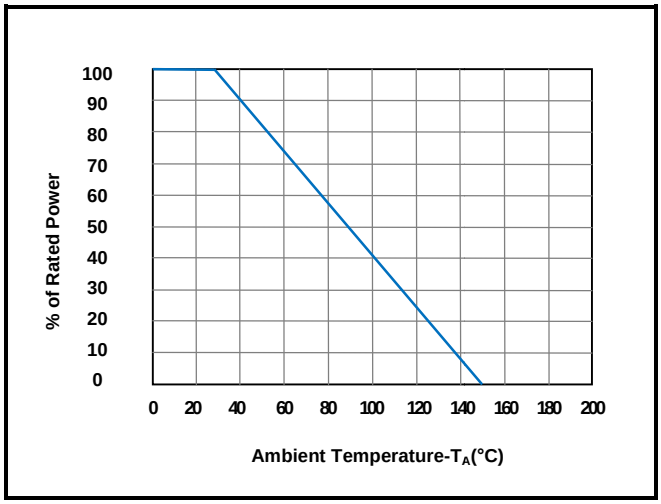
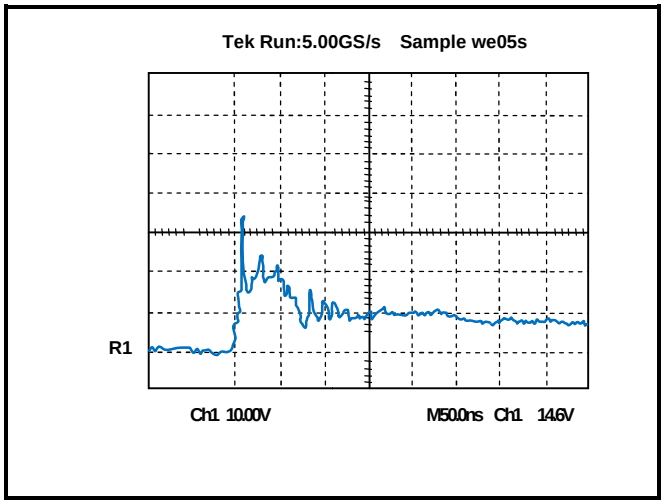
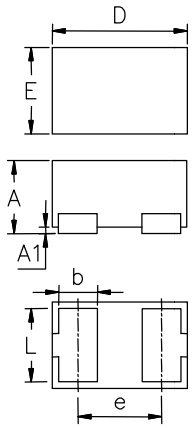


Figure 4.ESD Clamping(8KV Contact per IEC61000-4-2)



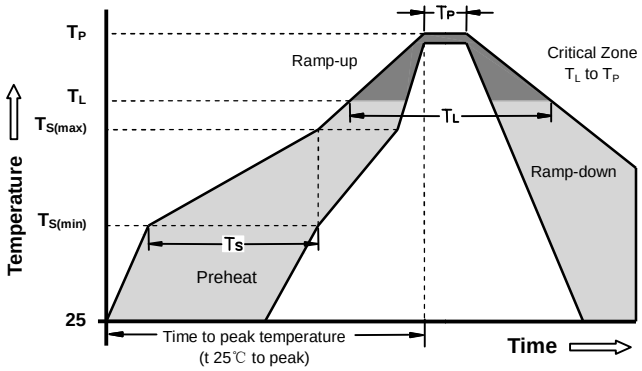
Dimensions



DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	0.34	0.44	0.013	0.017
A1	-	0.05		0.002
D	1.00BSC		0.039BSC	
E	0.60BSC		0.024BSC	
b	0.20	0.30	0.008	0.012
L	0.43	0.53	0.017	0.021
e	0.65 BSC		0.026 BSC	

Part Number	Component package	Marking	Quantity	Reel Size	Molding compound flammability rating	Lead Finish
RLSD92Q121C	SOD-882	S	12000	7 inch	UL 94V-0	Lead Free

Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Condition		Pb - Free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 -180 Seconds
Average ramp up rate (Liquids Temp T_L) to peak		3°C/second max
$T_{S(max)}$ to TL - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquids)	217°C
	- Time (min to max) (t_s)	60 -150 Seconds
Peak Temperature (T_P)		260 +0/-5°C
Time within 5°C of actual peak Temperature (t_p)		20 - 40 Seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max
Do not exceed		280°C